ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Par	PC. Bannockl	burn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	vithin the manufactu level materials for v	rer listed i which the r	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
PC Web Site for Information on IPC-1752 Standard Fo			Form Type Distribute						ials and M	ials and Mfg Information				
Supplier Information														
Company name* Comp			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi											2024-04-29			
Contact Name	tet Name Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards Product Envir			iro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repre			sentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro-			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	М	anufacturing Site		Weight*	UOM	Unit Type	
	NZQA5	NZQA5V6AXV5T1G LOW CAP QUAD		D ZEN SOT553	}	2024-04-29		C	CN1		2.678	mg	Each	
Ianufacturing Proccess Informa	tion						-	·						
Terminal Plating / Grid Array Ma	aterial	ial Terminal Base Alloy		J-STD-020 MSI	Rating	Peak Proce	A Process Body Temperature Max Time at Peal		k Tempera	ture Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	secor	nds 3			
omments														
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.03	mg	
Lead Frame	1.22	mg	В	Nickel (Ni)	7440-02-0		0.4941	mg	
			Supplier	Iron (Fe)	7439-89-6		0.6771	mg	
			Supplier	Copper (Cu)	7440-50-8		0.0488	mg	
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg	
Plating	0.003	mg	Supplier	Tin (Sn)	7440-31-5		0.003	mg	
Wire Bond - Cu	0.025	mg	Supplier	Copper (Cu)	7440-50-8		0.025	mg	